

SWITCHING REGULATOR CONTROL CIRCUIT FOR 500 kHz OPERATION

μ PC1099 is a control IC for the high performance switching power supply equipped with high speed/high sensitivity protection circuit. Control ICs for the high performance switching power supply have 3 series of μ PC1099, 1905, 1906. The features of μ PC1099 are as follows:

Low voltage start up (11 V TYP.) → Suited for flyback mode converter, DC-DC converter, etc.

CONTROL IC FAMILY FOR THE HIGH PERFORMANCE SWITCHING POWER SUPPLY

PART NUMBER	SUPPLY VOLTAGE	START-UP THRESHOLD VOLTAGE	THRESHOLD HYSTERESIS	OVER CURRENT LATCH PROTECTION MODE
μ PC1099	26 V	11 V	3 V	Pulse by pulse current limiting
μ PC1905	31 V	16.5 V	6.5 V	Pulse by pulse current limiting
μ PC1906	31 V	16.5 V	6.5 V	Shut down and V_{CC} reset

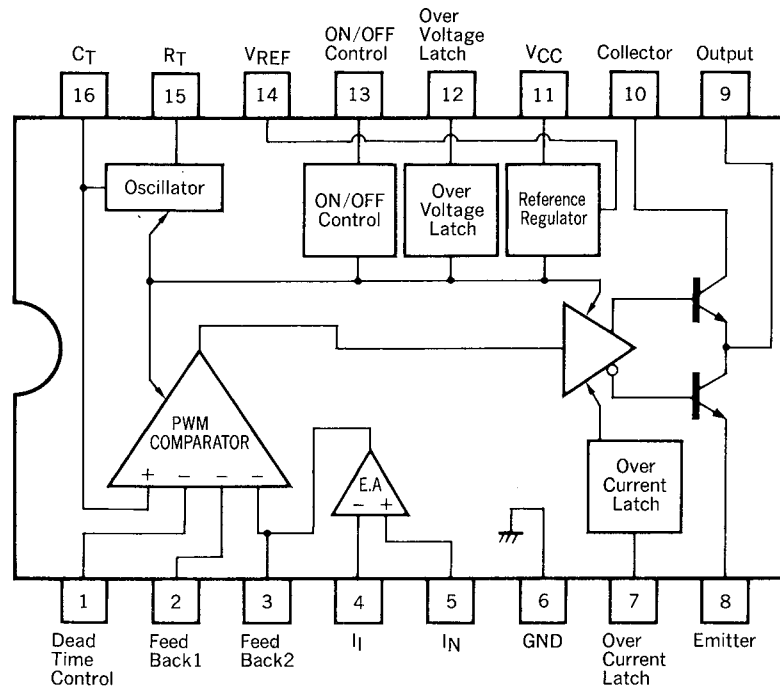
FEATURES

- Directly drive power MOS FET (totem pole circuit adopted)
- Under voltage lockout circuit incorporated
- Pulse by pulse over current latch circuit incorporated
- Remote control circuit incorporated
- Over voltage latch circuit incorporated
- Error amplifier incorporated

PART NUMBER	PACKAGE	QUALITY GRADE
μ PC1099CX	16 pin plastic DIP (300 mil)	Standard
μ PC1099GS	16 pin plastic SOP (300 mil)	

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

PIN CONNECTION DIAGRAM (Top View)



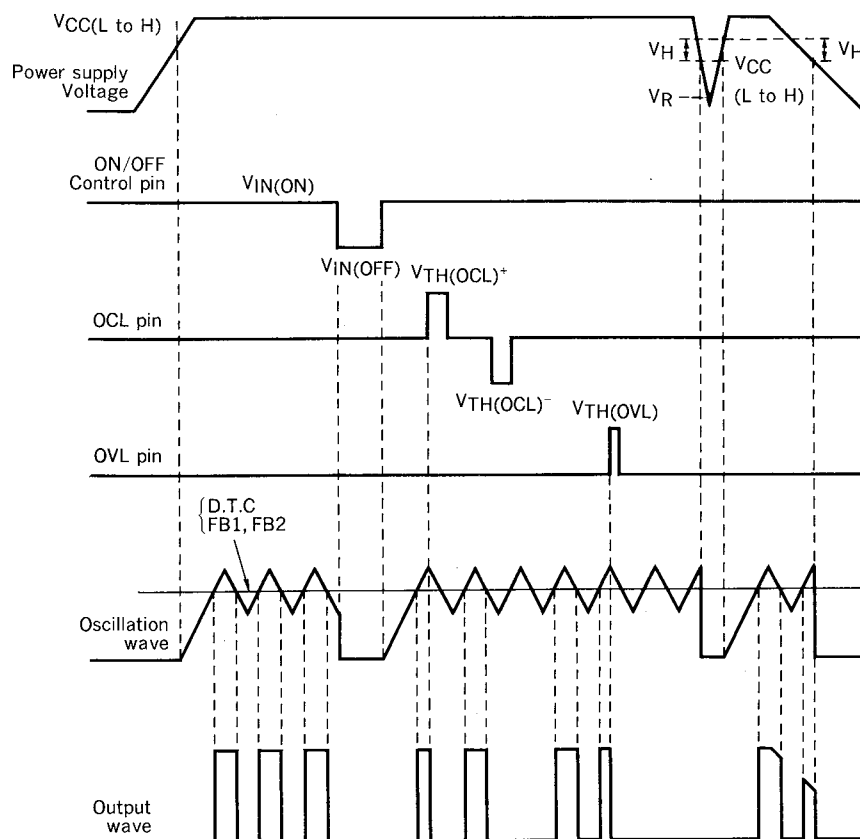
ABSOLUTE MAXIMUM RATING ($T_a = 25^\circ\text{C}$)

PARAMETER		SYMBOL	RATING	UNIT
Supply Voltage		V_{CC}	26	V
Output Voltage		V_C	26	V
Output Current		$I_C(\text{DC})$	100	mA
Peak Output Current		$I_C(\text{peak})$	1.2	A
Total Power Dissipation	μPC1099CX	$P_T(T_a = 25^\circ\text{C})$	1 000	mW
	μPC1099GS	$P_T(T_a = 25^\circ\text{C})$	694	mW
Operation Temperature		T_{opt}	-20 to +85	$^\circ\text{C}$
Storage Temperature		T_{stg}	-55 to +150	$^\circ\text{C}$

RECOMMENDED OPERATION REQUIREMENTS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage	V_{CC}	11.5	15	24	V
Oscillation Frequency	f_{OSC}	50	200	500	kHz
Output Load Capacitance	C_L	—	2 200	3 000	pF

OPERATION WAVES

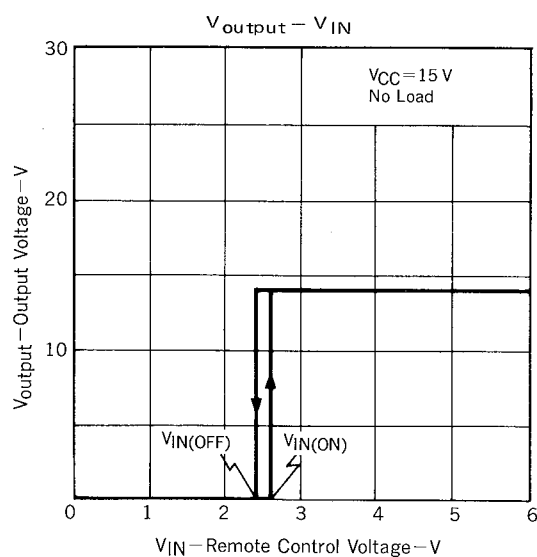
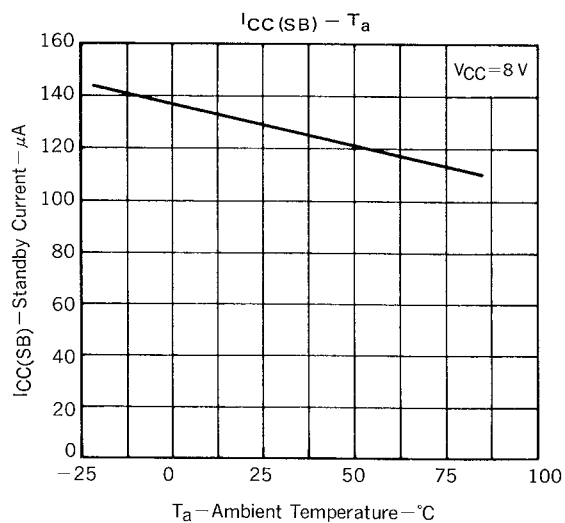
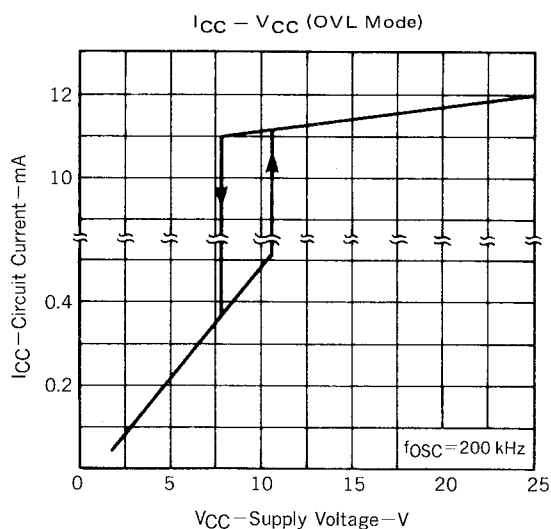
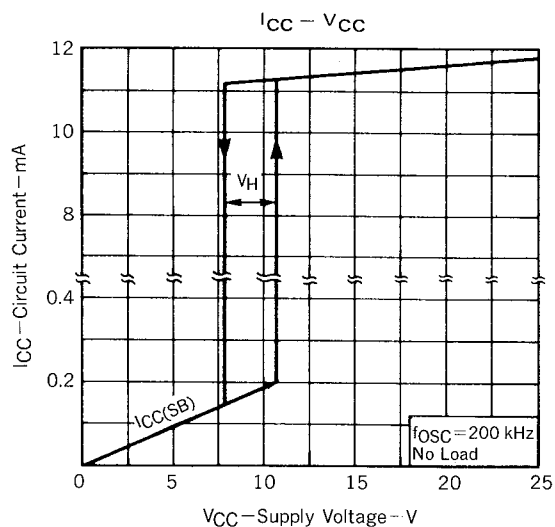
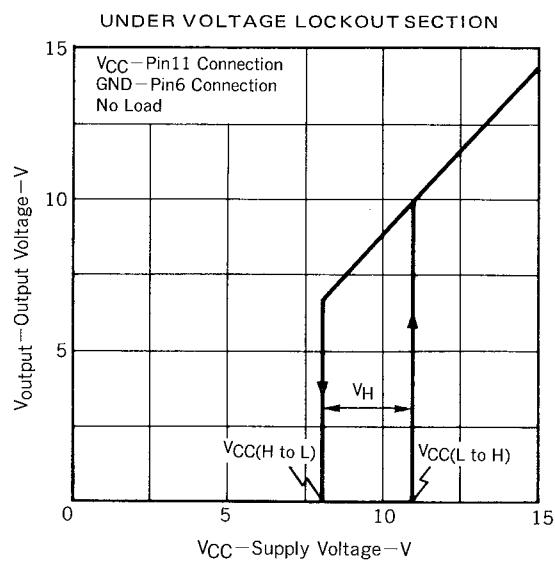
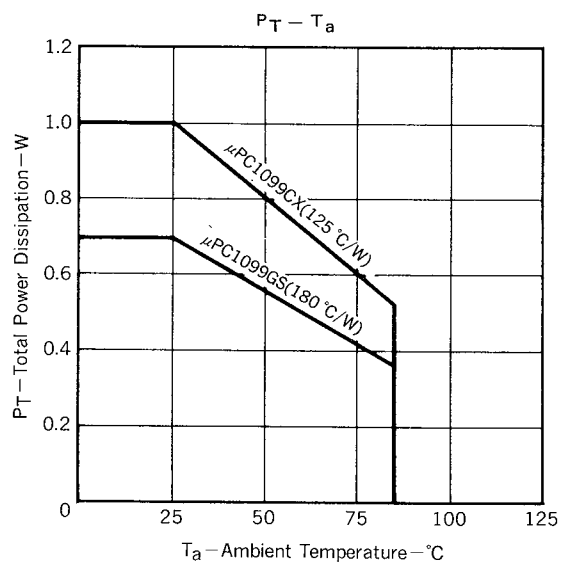


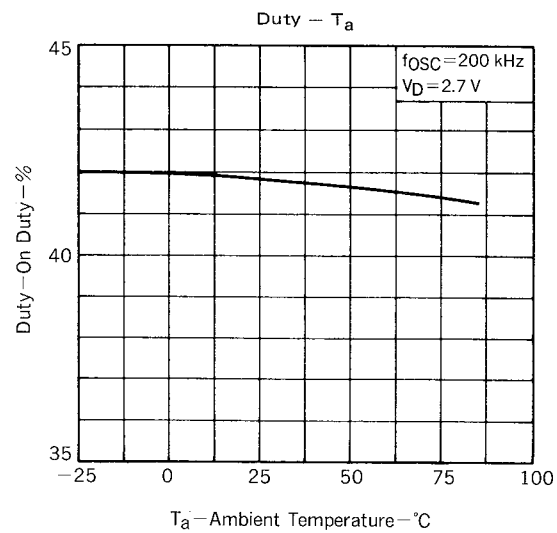
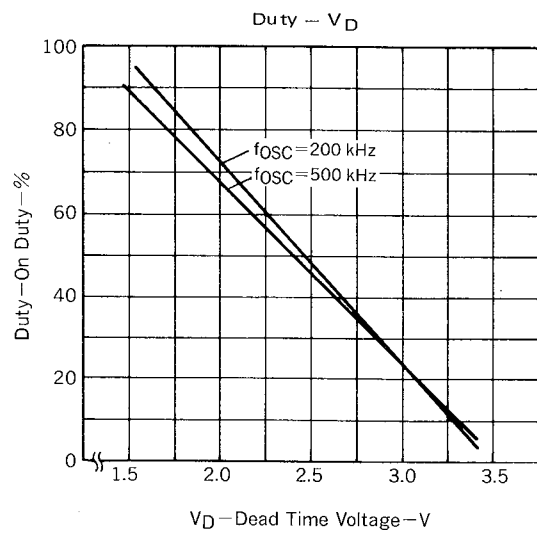
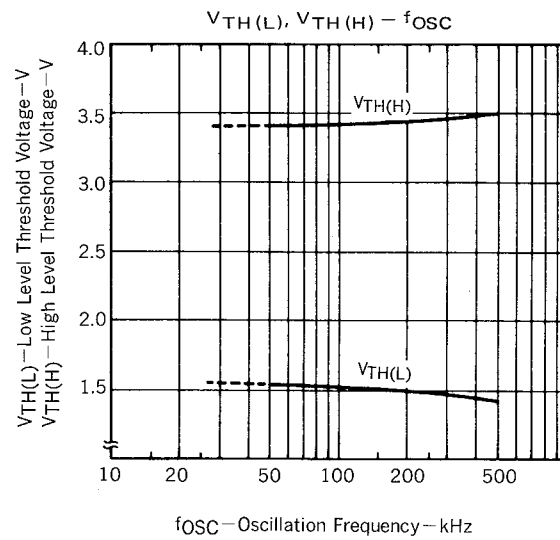
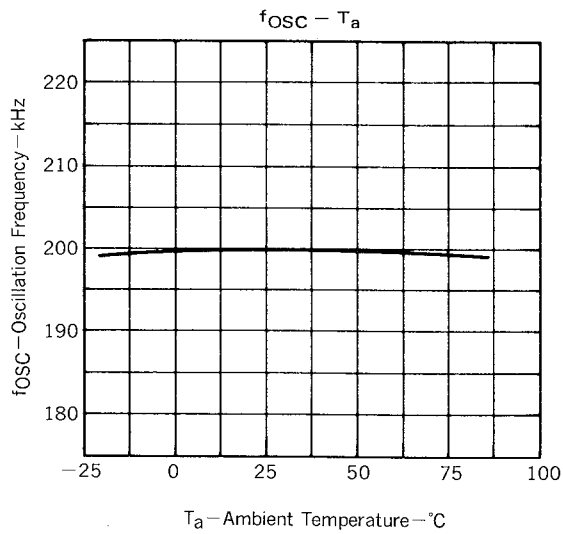
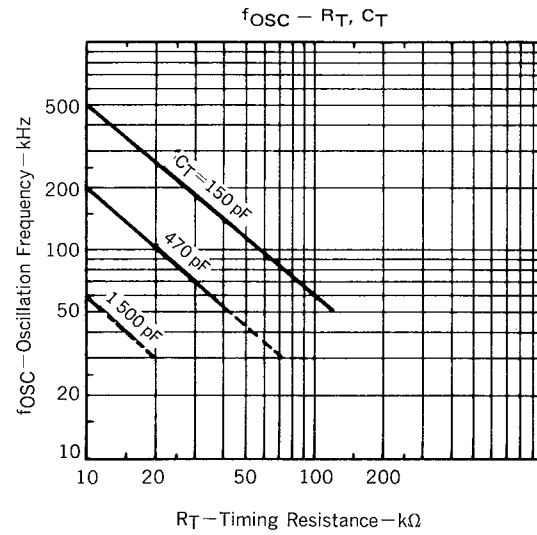
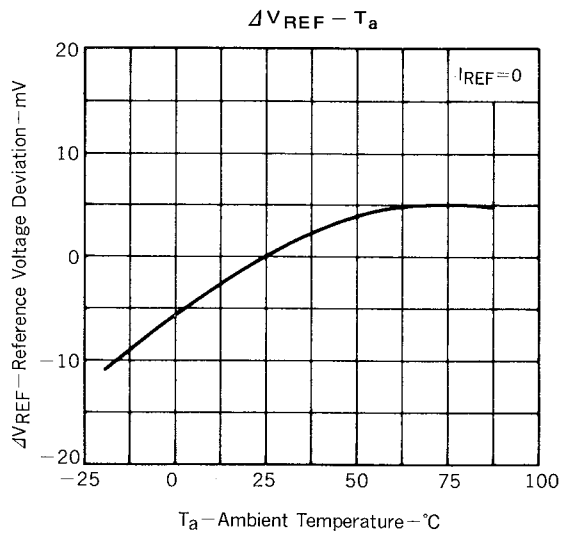
ELECTRICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$, $V_{CC} = 15\text{ V}$, $C_T = 470\text{ pF}$, $R_T \cong 10\text{ k}\Omega$, $f_{OSC} = 200\text{ kHz}$)

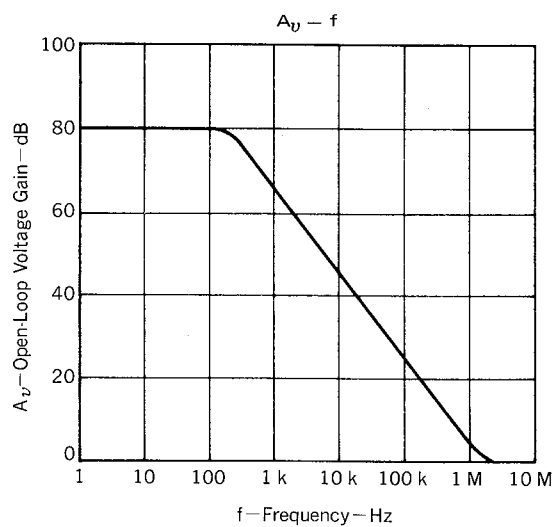
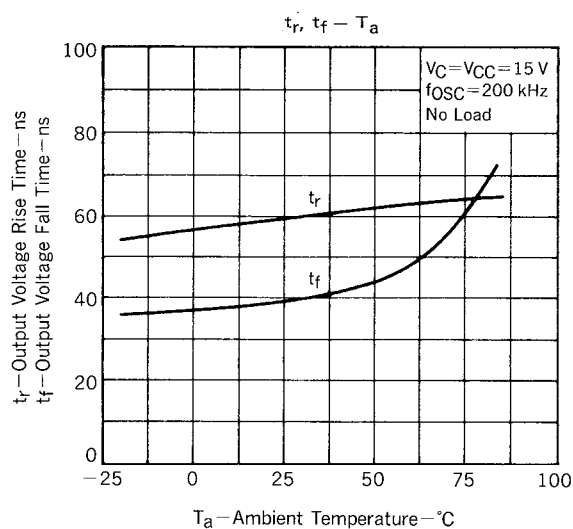
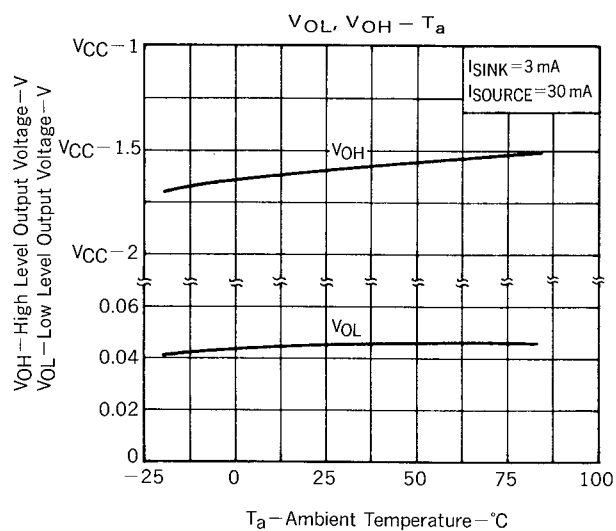
BLOCK	PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Total	Standby Current	$I_{CC(SB)}$	0.05	0.1	0.2	mA	$V_{CC} = 8\text{ V}$, $-10^\circ\text{C} \leq T_a \leq 85^\circ\text{C}$
	Circuit Current at OVL Operation Mode	$I_{CC(OVL)}$		10		mA	
	Circuit Current at Off Mode	$I_{CC(OFF)}$		10		mA	
	Circuit Current	I_{CC}		10	15	mA	$V_{CC} = V_C = 24\text{ V}$, $V_D = 2.7\text{ V}$, no load
Under Voltage Lockout Section	Start-Up Threshold Voltage	$V_{CC(L\text{ to }H)}$	10.5	11	11.5	V	
	Threshold Hysteresis	V_H	2.8	3	3.2	V	
Reference Voltage Section	Output Voltage	V_{REF}	4.8	5	5.2	V	$I_{REF} = 0$
	Line Regulation	REG_{IN}		1	10	mV	$11.5\text{ V} \leq V_{CC} \leq 20\text{ V}$, $I_{REF} = 0$
	Load Regulation	REG_L		6.5	12	mV	$0 \leq I_{REF} \leq 3\text{ mA}$
	Output Voltage Temperature Coefficient	$V_{REF}/\Delta T$		400	700	$\mu\text{V}/^\circ\text{C}$	$I_{REF} = 0$, $-10^\circ\text{C} \leq T_a \leq +85^\circ\text{C}$
	Short Circuit Current	$I_{O\text{ short}}$		13		mA	$V_{REF} = 0$
PWM Section	Input Bias Current	I_B			10	μA	
	Low Level Threshold Voltage	$V_{TH(L)}$		1.5		V	
	High Level Threshold Voltage	$V_{TH(H)}$		3.5		V	
	Dead Time Temperature Coefficient	$\Delta DT/\Delta T$		3		%	$V_D = 0.54 V_{REF}$, $-10^\circ\text{C} \leq T_a \leq +85^\circ\text{C}$
Oscillator Section	Oscillation Frequency	f_{OSC}	180	200	220	kHz	
	Frequency Line Regulation	$\Delta f/\Delta V_{CC}$		1		%	$11.5\text{ V} \leq V_{CC} \leq 24\text{ V}$
	Frequency Temperature Coefficient	$\Delta f/\Delta T$		2	5	%	$-10^\circ\text{C} \leq T_a \leq +85^\circ\text{C}$
Output Section	Low Level Output Voltage	V_{OL}			0.5	V	$I_{SINK} = 3\text{ mA}$, $V_{CC} = V_C$
	High Level Output Voltage	V_{OH}		$V_{CC}-1.6$		V	$I_{SOURCE} = 30\text{ mA}$, $V_{CC} = V_C$
	Output Voltage Rise Time	t_r		60		ns	$R_L = 15\ \Omega$, $C_L = 2\ 200\text{ pF}$
	Output Voltage Fall Time	t_f		40		ns	$V_{CC} = V_C$
Remote Control Section	Input Voltage at Output ON	$V_{IN(ON)}$	2.4	2.6	2.8	V	
	Input Voltage at Output OFF	$V_{IN(OFF)}$	2.2	2.4	2.6	V	
	Hysteresis Width	V_H	0.1	0.2	0.3	V	
Over Voltage Latch Section	Over Voltage Threshold Voltage	$V_{TH(OVL)}$	2.0	2.4	2.8	V	$-10^\circ\text{C} \leq T_a \leq +85^\circ\text{C}$
	Input Bias Current	$I_B(OVL)$			4	μA	OVL pin voltage = $V_{TH(OVL)}$
	OVL Reset Voltage	$V_R(OVL)$		2		V	
	Delay to Output	$t_d(OVL)$		750		ns	
Over Current Latch Section	Over Current Threshold Voltage	$V_{TH(OCL)}^+$	200	220	240	mV	$-10^\circ\text{C} \leq T_a \leq +85^\circ\text{C}$
	Over Current Threshold Voltage	$V_{TH(OCL)}^-$	-230	-210	-190	mV	$-10^\circ\text{C} \leq T_a \leq +85^\circ\text{C}$
	OCL Pin Output Current	$I_B(OCL)$		250		μA	
	Delay to Output	$t_d(OCL)^+$		120		ns	
	Delay to Output	$t_d(OCL)^-$		160		ns	

BLOCK	PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Error Amplifier Section	Input Bias Current	I_B (AMP)			1	μA	$V_{IN} = 2.5 \text{ V}$
	Open-Loop Voltage Gain	A_v	60	80		dB	$V_{FB} = 2.9 \text{ V}$
	Unit Gain Bandwidth	f_{unity}	1	1.6		MHz	
	High Level Output Voltage	V_{om}^+	3.0			V	
	Low Level Output Voltage	V_{om}^-			1.0	V	
	Common Mode Input Voltage Range	V_{ICM}^+	3			V	$11.5 \text{ V} \leq V_{CC} \leq 24 \text{ V},$ $-10^\circ \text{C} \leq T_a \leq +85^\circ \text{C}$
	Common Mode Input Voltage Range	V_{ICM}^-			-0.3	V	

TYPICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$, $V_{CC} = 15\text{ V}$)

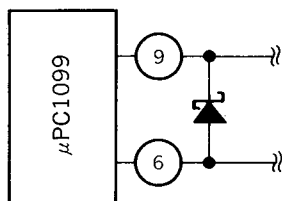






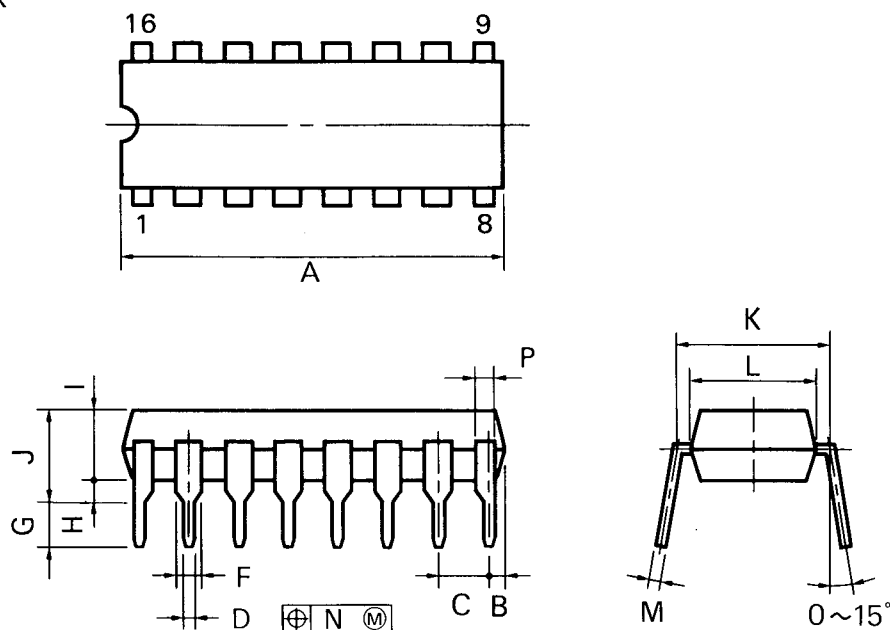
NOTE: When under-shoot voltage at pin 9 occurs, it must be cramped to prevent from wrong operation. See Fig. 1.

Fig. 1



16PIN PLASTIC DIP (300 mil)

μPC1099CX



P16C-100-300B

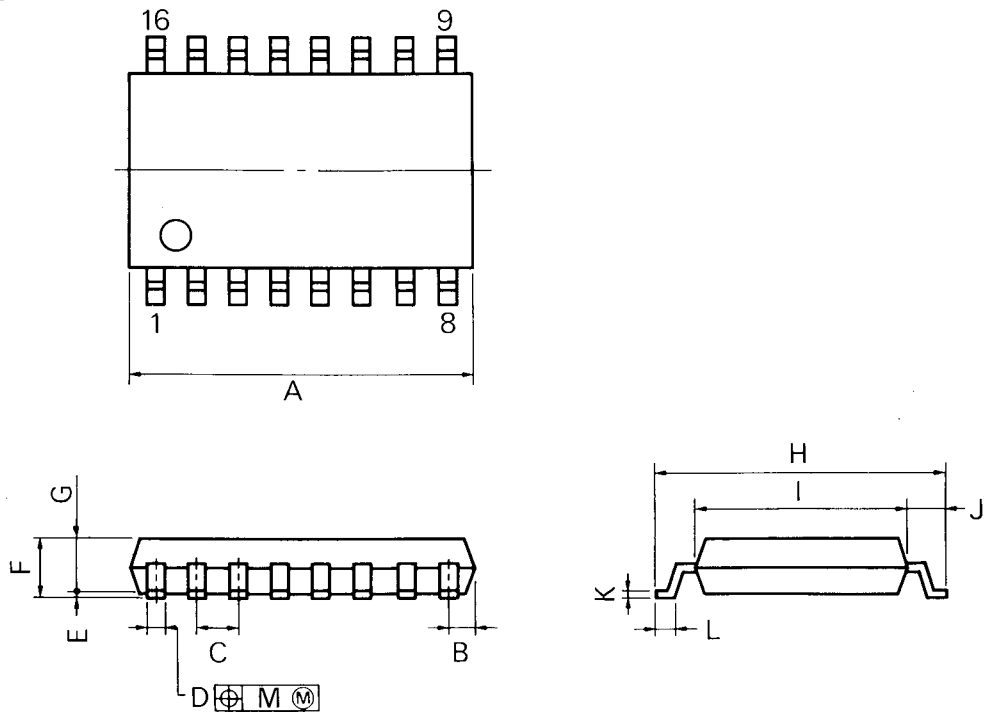
NOTES

- 1) Each lead centerline is located within 0.25 mm (0.01 inch) of its true position (T.P.) at maximum material condition.
- 2) Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS	INCHES
A	20.32 MAX.	0.800 MAX.
B	1.27 MAX.	0.050 MAX.
C	2.54 (T.P.)	0.100 (T.P.)
D	0.50 ^{+0.10} _{-0.05}	0.020 ^{+0.004} _{-0.005}
F	1.1 MIN.	0.043 MIN.
G	3.5 ^{+0.3}	0.138 ^{+0.012}
H	0.51 MIN.	0.020 MIN.
I	4.31 MAX.	0.170 MAX.
J	5.08 MAX.	0.200 MAX.
K	7.62 (T.P.)	0.300 (T.P.)
L	6.5	0.256
M	0.25 ^{+0.10} _{-0.05}	0.010 ^{+0.004} _{-0.003}
N	0.25	0.01
P	1.1 MIN.	0.043 MIN.

16PIN PLASTIC SOP (300 mil)

μPC1099GS



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

P16GM-50-300B-1

ITEM	MILLIMETERS	INCHES
A	10.46 MAX.	0.412 MAX.
B	0.78 MAX.	0.031 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ^{+0.10} _{-0.06}	0.016 ^{+0.004} _{-0.003}
E	0.1 ^{±0.1}	0.004 ^{±0.004}
F	1.8 MAX.	0.071 MAX.
G	1.55	0.061
H	7.7 ^{±0.3}	0.303 ^{±0.012}
I	5.6	0.220
J	1.1	0.043
K	0.20 ^{+0.10} _{-0.05}	0.008 ^{+0.004} _{-0.002}
L	0.6 ^{±0.2}	0.024 ^{+0.008} _{-0.009}
M	0.12	0.005

RECOMMENDED SOLDERING CONDITIONS

The following conditions (see table below) must be set when soldering this product.

Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

TYPES OF SURFACE MOUNT DEVICE

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (IEI-1207).

μPC1099GS

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak package's surface temperature : 230 °C or below, Reflow time : 30 seconds or below (210 °C or higher), Number of reflow process : 1, Exposure limit* : None	IR30-00-1
VPS	Peak package's surface temperature : 215 °C or below, Reflow time : 40 seconds or below (200 °C or higher), Number of reflow process : 1, Exposure limit* : None	VP15-00-1

* : Exposure limit before soldering after dry-pack package is opened.

Storage conditions : 25 °C and relative humidity at 65 % or less.

Note: Do not apply more than a single process at once, except for "Partial heating method".

TYPES OF THROUGH HOLE MOUNT DEVICE

μPC1099CX

Soldering process	Soldering conditions	Symbol
Wave soldering	Solder temperature : 260 °C or below, Flow time : 10 seconds or below	

[MEMO]

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Application examples recommended by NEC Corporation

Standard: Computer, Office equipment, Communication equipment, Test and Measurement equipment, Machine tools, Industrial robots, Audio and Visual equipment, Other consumer products, etc.

Special: Automotive and Transportation equipment, Traffic control systems, Antidisaster systems, Anti-crime systems, etc.